

#### DESCRIPTION

The SM220AF~SM2200AF are available in SMAF package.

# FEATURES

- Metal silicon junction, majority carrier conduction
- For surface mounted applications
- Low power loss, high efficiency
- High forward surge current capability
- For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications
- Available in SMAF package

#### ORDERING INFORMATION

Package Type	Part Number				
SMAF	SM220AF				
	SM240AF				
	SM260AF				
	SM280AF				
	SM2100AF				
	SM2120AF				
	SM2150AF				
	SM2200AF				
Note	SPQ: 3,000pcs/Reel				
AiT provides all RoHS Compliant Products					

# MECHANICAL DATA

Case: SMAF

Terminals: Solderable per MIL-STD-750, Method 2026 Approx. Weight: 27mg 0.00086oz

# PIN DESCRIPTION





# ABSOLUTE MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz resistive or inductive load, for capacitivederate by 20 %

Parameter		Symbol	SM 220AF	SM 240AF	SM 260AF	SM 280AF	SM 2100AF	SM 2120AF	SM 2150AF	SM 2200AF	Unit
Maximum Repetitive Peak Reve Voltage	V <sub>RRM</sub>	20	40	60	80	100	120	150	200	V	
Maximum RMS Voltage	V <sub>RMS</sub>	14	28	42	56	70	84	105	140	V	
Maximum DC Blocking Voltage	$V_{\text{DC}}$	20	40	60	80	100	120	150	200	V	
Maximum Average Forward Rec Current	I <sub>F(AV)</sub>	2.0							А		
Peak Forward Surge Current,8.3 Single Half Sine-wave Superimp on Rated Load (JEDEC method	IFSM	50 40						А			
Max Instantaneous Forward Voltage at 2A		$V_{F}$	0.	55	0.70		0.85		0.95		V
Maximum DC Reverse Current at Rated DC Reverse Voltage	T <sub>A</sub> =25°C T <sub>A</sub> =100°C	I <sub>R</sub>	0.5 5		0.3 3				mA		
Typical Junction Capacitance <sup>NO</sup>	Cj	220 80				pF					
Operating Junction Temperature	ТJ	-55 to +125							°C		
Storage Temperature Range	Tstg	-55 to +150							°C		

NOTE1: Measured at 1MHz and applied reverse voltage of 4V D.C



#### TYPICAL PERFORMANCE CHARACTERISTICS

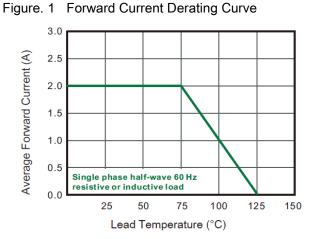
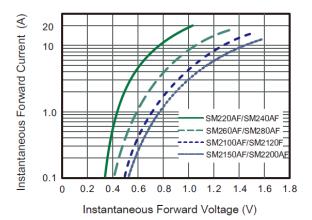
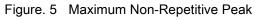
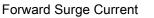


Figure. 3 Typical Forward Characteristic







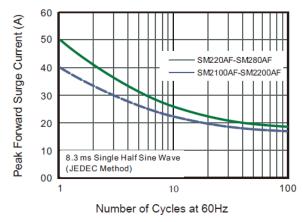


Figure. 2 Typical Reverse Characteristics

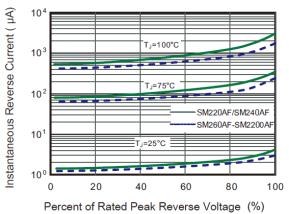
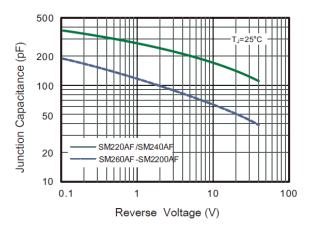


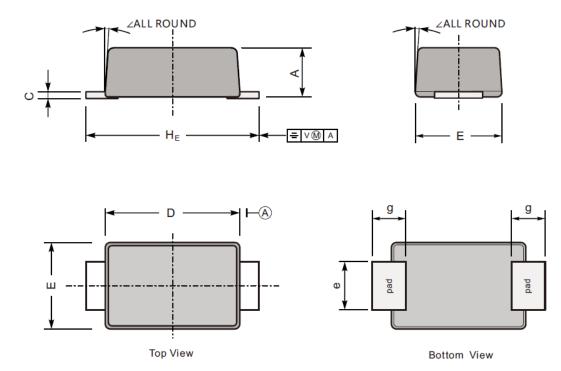
Figure. 4 Typical Junction Capacitance



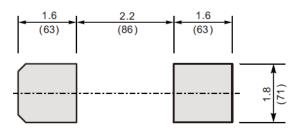


# PACKAGE INFORMATION

Dimension in SMAF Package (Unit: mm)



The recommended mounting pad size



Unit: mm (mil)

UNIT		А	С	D	Е	е	g	HE	2
mm	Min	1.1	0.20	3.7	2.7	1.6	1.2	4.9	<b>7</b> °
	Max	0.9	0.12	3.3	2.4	1.3	0.8	4.4	
mil	Min	43	7.9	146	106	63	47	193	/
	Max	35	4.7	130	94	51	31	173	



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